



Material Content Data Sheet



Halogen-Free

Sales Product Name	BTT6200-1ENA	Issued	11. April 2021
MA#	MA001827476		
Package	PG-TDSO-8-31	Weight*	67.23 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.977	1.45	1.45	14528	14528
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		141	
	non noble metal	zinc	7440-66-6	0.038	0.06		565	
	non noble metal	iron	7439-89-6	0.760	1.13		11302	
	non noble metal	copper	7440-50-8	30.851	45.88	47.08	458894	470902
wire	non noble metal	copper	7440-50-8	0.194	0.29	0.29	2889	2889
encapsulation	organic material	carbon black	1333-86-4	0.098	0.15		1456	
	plastics	epoxy resin	-	3.817	5.68		56778	
	inorganic material	silicondioxide	60676-86-0	28.709	42.70	48.53	427045	485279
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7396	7396
plating	noble metal	silver	7440-22-4	0.825	1.23	1.23	12268	12268
glue	plastics	epoxy resin	-	0.079	0.12		1179	
	noble metal	silver	7440-22-4	0.374	0.56	0.68	5559	6738
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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